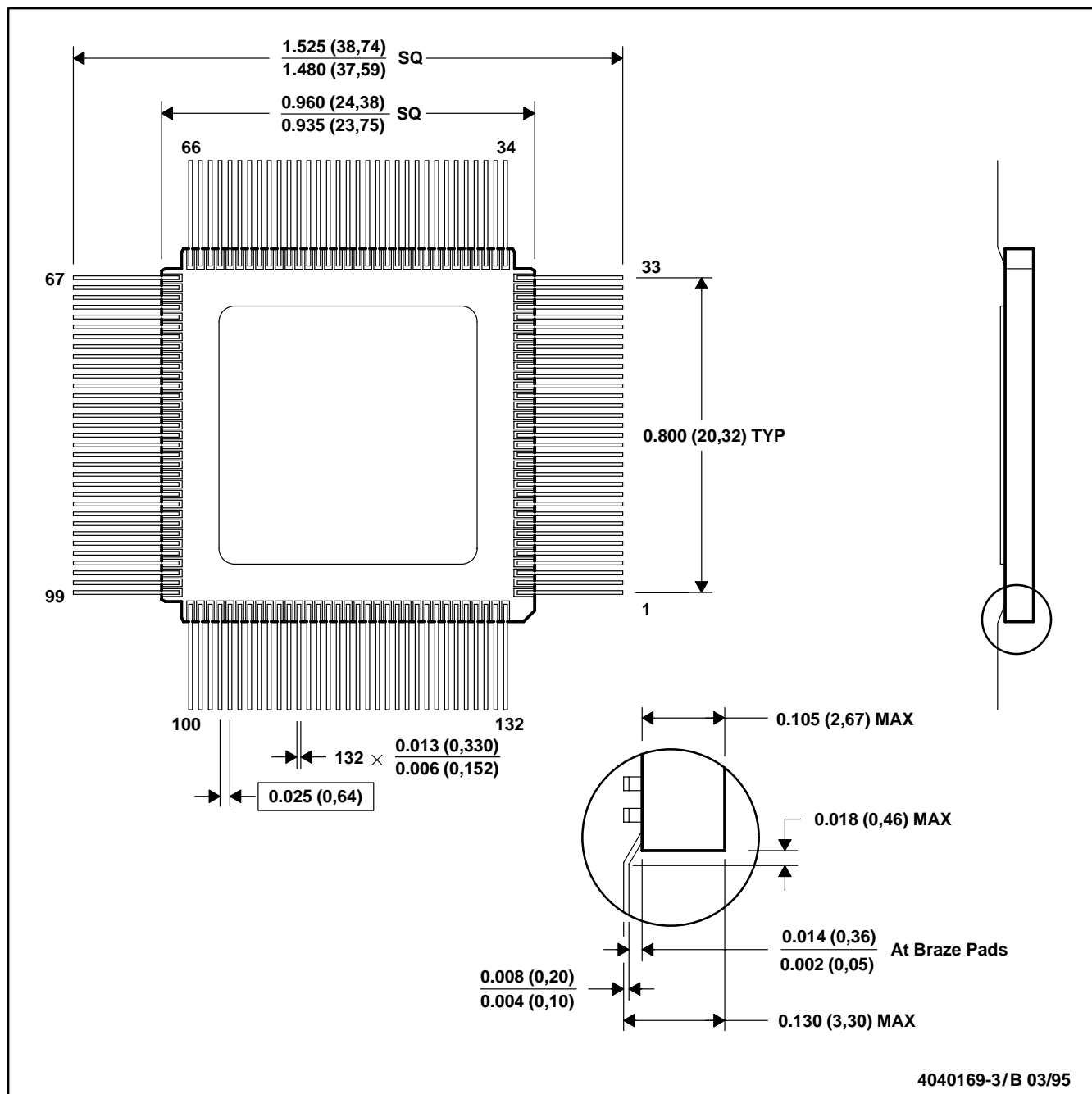


HT (S-CQFP-F132)

CERAMIC QUAD FLATPACK



NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package is hermetically sealed with a metal lid.
 D. The terminals are gold plated.
 E. Falls within JEDEC MO-090 AB

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